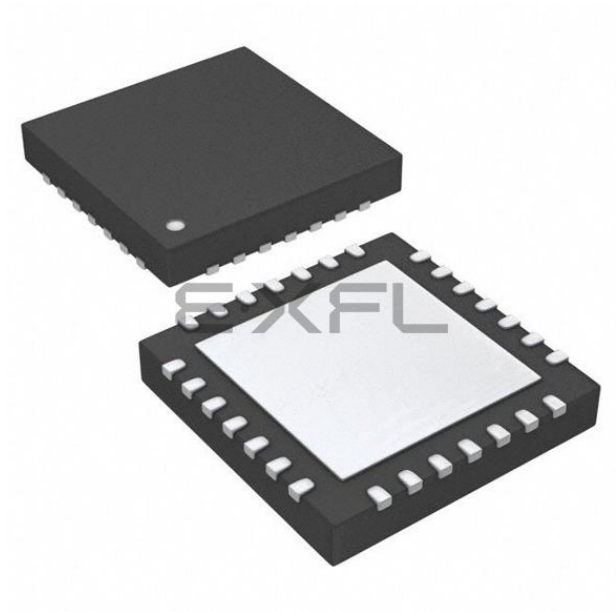

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	15
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1847t-i-mv

3.3 Register Definitions: Status

REGISTER 3-1: STATUS: STATUS REGISTER

U-0	U-0	U-0	R-1/q	R-1/q	R/W-0/u	R/W-0/u	R/W-0/u
—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC(1)	C(1)
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **$\overline{TO}$:** Time-out bit
- 1 = After power-up, CLRWDT instruction or SLEEP instruction
- 0 = A WDT time-out occurred

bit 3 **$\overline{PD}$:** Power-down bit
- 1 = After power-up or by the CLRWDT instruction
- 0 = By execution of the SLEEP instruction

bit 2 **Z:** Zero bit
- 1 = The result of an arithmetic or logic operation is zero
- 0 = The result of an arithmetic or logic operation is not zero

bit 1 **DC:** Digit Carry/$\overline{\text{Digit Borrow}}$ bit(1)
- 1 = A carry-out from the 4th low-order bit of the result occurred
- 0 = No carry-out from the 4th low-order bit of the result

bit 0 **C:** Carry/$\overline{\text{Borrow}}$ bit(1)
- 1 = A carry-out from the Most Significant bit of the result occurred
- 0 = No carry-out from the Most Significant bit of the result occurred

Note 1: For $\overline{\text{Borrow}}$, the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high-order or low-order bit of the source register.

4.2 Register Definitions: Configuration Words

REGISTER 4-1: CONFIG1: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
FCMEN	IESO	$\overline{\text{CLKOUTEN}}$	BOREN<1:0>		$\overline{\text{CPD}}$
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	-n = Value when blank or after Bulk Erase

bit 13 **FCMEN:** Fail-Safe Clock Monitor Enable bit
1 = Fail-Safe Clock Monitor and internal/external switchover are both enabled.
0 = Fail-Safe Clock Monitor is disabled

bit 12 **IESO:** Internal External Switchover bit
1 = Internal/External Switchover mode is enabled
0 = Internal/External Switchover mode is disabled

bit 11 **$\overline{\text{CLKOUTEN}}$:** Clock Out Enable bit
If FOSC configuration bits are set to LP, XT, HS modes:
This bit is ignored, CLKOUT function is disabled. Oscillator function on the CLKOUT pin.
All other FOSC modes:
1 = CLKOUT function is disabled. I/O function on the CLKOUT pin.
0 = CLKOUT function is enabled on the CLKOUT pin

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR enabled
10 = BOR enabled during operation and disabled in Sleep
01 = BOR controlled by SBOREN bit of the BORCON register
00 = BOR disabled

bit 8 **$\overline{\text{CPD}}$:** Data Code Protection bit(1)
1 = Data memory code protection is disabled
0 = Data memory code protection is enabled

bit 7 **$\overline{\text{CP}}$:** Code Protection bit
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 6 **MCLRE:** $\overline{\text{MCLR}}$/V_{PP} Pin Function Select bit
If LVP bit = 1:
This bit is ignored.
If LVP bit = 0:
1 = $\overline{\text{MCLR}}$/V_{PP} pin function is $\overline{\text{MCLR}}$; Weak pull-up enabled.
0 = $\overline{\text{MCLR}}$/V_{PP} pin function is digital input; $\overline{\text{MCLR}}$ internally disabled; Weak pull-up under control of WPUE3 bit.

bit 5 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 4-3 **WDTE<1:0>:** Watchdog Timer Enable bit
11 = WDT enabled
10 = WDT enabled while running and disabled in Sleep
01 = WDT controlled by the SWDTEN bit in the WDTCON register
00 = WDT disabled

7.11 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON register are updated to indicate the cause of the Reset. Table 7-3 and Table 7-4 show the Reset conditions of these registers.

TABLE 7-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

STKOVF	STKUNF	$\overline{\text{RMCLR}}$	$\overline{\text{RI}}$	$\overline{\text{POR}}$	$\overline{\text{BOR}}$	$\overline{\text{TO}}$	$\overline{\text{PD}}$	Condition
0	0	1	1	0	x	1	1	Power-on Reset
0	0	1	1	0	x	0	x	Illegal, $\overline{\text{TO}}$ is set on $\overline{\text{POR}}$
0	0	1	1	0	x	x	0	Illegal, $\overline{\text{PD}}$ is set on $\overline{\text{POR}}$
0	0	1	1	u	0	1	1	Brown-out Reset
u	u	u	u	u	u	0	u	WDT Reset
u	u	u	u	u	u	0	0	WDT Wake-up from Sleep
u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep
u	u	0	u	u	u	u	u	$\overline{\text{MCLR}}$ Reset during normal operation
u	u	0	u	u	u	1	0	$\overline{\text{MCLR}}$ Reset during Sleep
u	u	u	0	u	u	u	u	RESET Instruction Executed
1	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)
u	1	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)

TABLE 7-4: RESET CONDITION FOR SPECIAL REGISTERS(2)

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	---1 1000	00-- 110x
$\overline{\text{MCLR}}$ Reset during normal operation	0000h	---u uuuu	uu-- 0uuu
$\overline{\text{MCLR}}$ Reset during Sleep	0000h	---1 0uuu	uu-- 0uuu
WDT Reset	0000h	---0 uuuu	uu-- uuuu
WDT Wake-up from Sleep	PC + 1	---0 0uuu	uu-- uuuu
Brown-out Reset	0000h	---1 1uuu	00-- 11u0
Interrupt Wake-up from Sleep	PC + 1(1)	---1 0uuu	uu-- uuuu
RESET Instruction Executed	0000h	---u uuuu	uu-- u0uu
Stack Overflow Reset (STVREN = 1)	0000h	---u uuuu	1u-- uuuu
Stack Underflow Reset (STVREN = 1)	0000h	---u uuuu	u1-- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

After the "BSF EECON1,WR" instruction, the processor requires two cycles to set up the write operation. The user must place two NOP instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms, only during the cycle in which the write takes place (i.e., the last word of the block write). This is not Sleep mode as the clocks and peripherals will continue to run. The processor does not stall when LWLO = 1, loading the write latches. After the write cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

FIGURE 11-2: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES

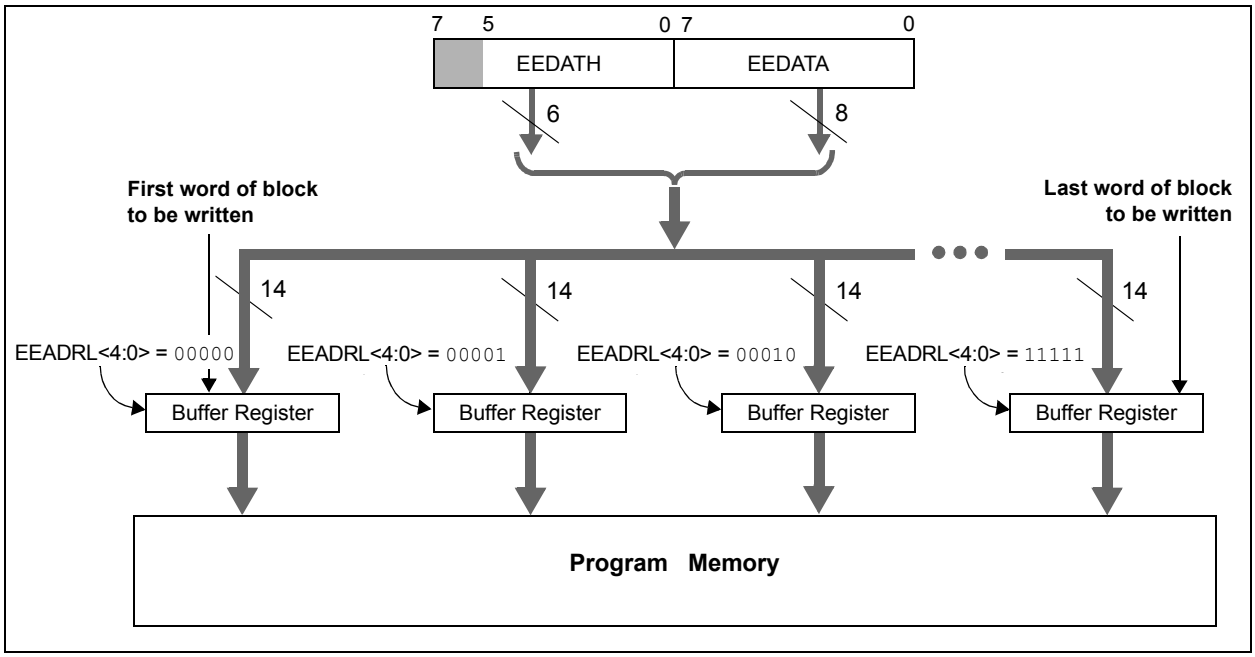


TABLE 17-1: SUMMARY OF REGISTERS ASSOCIATED WITH THE DAC MODULE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		134
DACCON0	DACEN	DACLPS	DACOE	—	DACPSS<1:0>		—	DACNSS	154
DACCON1	—	—	—	DACR<4:0>					154

Legend: — = unimplemented, read as '0'. Shaded cells are unused with the DAC module.

23.5 Carrier Source Polarity Select

The signal provided from any selected input source for the carrier high and carrier low signals can be inverted. Inverting the signal for the carrier high source is enabled by setting the MDCHPOL bit of the MDCARH register. Inverting the signal for the carrier low source is enabled by setting the MDCLPOL bit of the MDCARL register.

23.6 Carrier Source Pin Disable

Some peripherals assert control over their corresponding output pin when they are enabled. For example, when the CCP1 module is enabled, the output of CCP1 is connected to the CCP1 pin.

This default connection to a pin can be disabled by setting the MDCHODIS bit in the MDCARH register for the carrier high source and the MDCLODIS bit in the MDCARL register for the carrier low source.

23.7 Programmable Modulator Data

The MDBIT of the MDCON register can be selected as the source for the modulator signal. This gives the user the ability to program the value used for modulation.

23.8 Modulator Source Pin Disable

The modulator source default connection to a pin can be disabled by setting the MDMSODIS bit in the MDSRC register.

23.9 Modulated Output Polarity

The modulated output signal provided on the MDOUT pin can also be inverted. Inverting the modulated output signal is enabled by setting the MDOPOL bit of the MDCON register.

23.10 Slew Rate Control

The slew rate limitation on the output port pin can be disabled. The slew rate limitation can be removed by clearing the MDSLR bit in the MDCON register.

23.11 Operation in Sleep Mode

The DSM module is not affected by Sleep mode. The DSM can still operate during Sleep, if the Carrier and Modulator input sources are also still operable during Sleep.

23.12 Effects of a Reset

Upon any device Reset, the Data Signal Modulator module is disabled. The user's firmware is responsible for initializing the module before enabling the output. The registers are reset to their default values.

25.5.2 SLAVE RECEPTION

When the R/$\overline{W}$ bit of a matching received address byte is clear, the R/$\overline{W}$ bit of the SSPxSTAT register is cleared. The received address is loaded into the SSPxBUF register and acknowledged.

When the overflow condition exists for a received address, then not Acknowledge is given. An overflow condition is defined as either bit BF of the SSPxSTAT register is set, or bit SSPOV of the SSPxCON1 register is set. The BOEN bit of the SSPxCON3 register modifies this operation. For more information see Register 25-4.

An MSSPx interrupt is generated for each transferred data byte. Flag bit, SSPxIF, must be cleared by software.

When the SEN bit of the SSPxCON2 register is set, SCLx will be held low (clock stretch) following each received byte. The clock must be released by setting the CKP bit of the SSPxCON1 register, except sometimes in 10-bit mode. See **Section 25.2.3 "SPI Master Mode"** for more detail.

25.5.2.1 7-bit Addressing Reception

This section describes a standard sequence of events for the MSSPx module configured as an I^2C Slave in 7-bit Addressing mode. Figure 25-14 and Figure 25-15 are used as visual references for this description.

This is a step by step process of what typically must be done to accomplish I^2C communication.

1. Start bit detected.
2. S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
3. Matching address with R/$\overline{W}$ bit clear is received.
4. The slave pulls SDAx low sending an $\overline{ACK}$ to the master, and sets SSPxIF bit.
5. Software clears the SSPxIF bit.
6. Software reads received address from SSPxBUF clearing the BF flag.
7. If SEN = 1; Slave software sets CKP bit to release the SCLx line.
8. The master clocks out a data byte.
9. Slave drives SDAx low sending an $\overline{ACK}$ to the master, and sets SSPxIF bit.
10. Software clears SSPxIF.
11. Software reads the received byte from SSPxBUF clearing BF.
12. Steps 8-12 are repeated for all received bytes from the Master.
13. Master sends Stop condition, setting P bit of SSPxSTAT, and the bus goes idle.

25.5.2.2 7-bit Reception with AHEN and DHEN

Slave device reception with AHEN and DHEN set operate the same as without these options with extra interrupts and clock stretching added after the 8th falling edge of SCLx. These additional interrupts allow the slave software to decide whether it wants to $\overline{ACK}$ the receive address or data byte, rather than the hardware. This functionality adds support for PMBus™ that was not present on previous versions of this module.

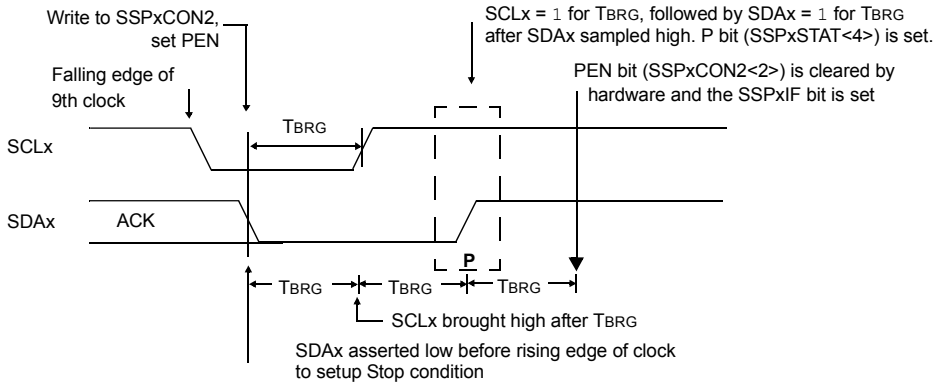
This list describes the steps that need to be taken by slave software to use these options for I^2C communication. Figure 25-16 displays a module using both address and data holding. Figure 25-17 includes the operation with the SEN bit of the SSPxCON2 register set.

1. S bit of SSPxSTAT is set; SSPxIF is set if interrupt on Start detect is enabled.
2. Matching address with R/$\overline{W}$ bit clear is clocked in. SSPxIF is set and CKP cleared after the 8th falling edge of SCLx.
3. Slave clears the SSPxIF.
4. Slave can look at the ACKTIM bit of the SSPxCON3 register to determine if the SSPxIF was after or before the $\overline{ACK}$.
5. Slave reads the address value from SSPxBUF, clearing the BF flag.
6. Slave sets $\overline{ACK}$ value clocked out to the master by setting ACKDT.
7. Slave releases the clock by setting CKP.
8. SSPxIF is set after an $\overline{ACK}$, not after a NACK.
9. If SEN = 1 the slave hardware will stretch the clock after the $\overline{ACK}$.
10. Slave clears SSPxIF.

Note: SSPxIF is still set after the 9th falling edge of SCLx even if there is no clock stretching and BF has been cleared. Only if NACK is sent to Master is SSPxIF not set

11. SSPxIF set and CKP cleared after 8th falling edge of SCLx for a received data byte.
12. Slave looks at ACKTIM bit of SSPxCON3 to determine the source of the interrupt.
13. Slave reads the received data from SSPxBUF clearing BF.
14. Steps 7-14 are the same for each received data byte.
15. Communication is ended by either the slave sending an $\overline{ACK}$ = 1, or the master sending a Stop condition. If a Stop is sent and Interrupt on Stop Detect is disabled, the slave will only know by polling the P bit of the SSPSTAT register.

FIGURE 25-31: STOP CONDITION RECEIVE OR TRANSMIT MODE



Note: TBRG = one Baud Rate Generator period.

25.6.10 SLEEP OPERATION

While in Sleep mode, the I^{2}C Slave module can receive addresses or data and when an address match or complete byte transfer occurs, wake the processor from Sleep (if the MSSPx interrupt is enabled).

25.6.11 EFFECTS OF A RESET

A Reset disables the MSSPx module and terminates the current transfer.

25.6.12 MULTI-MASTER MODE

In Multi-Master mode, the interrupt generation on the detection of the Start and Stop conditions allows the determination of when the bus is free. The Stop (P) and Start (S) bits are cleared from a Reset or when the MSSPx module is disabled. Control of the I^{2}C bus may be taken when the P bit of the SSPxSTAT register is set, or the bus is Idle, with both the S and P bits clear. When the bus is busy, enabling the SSPx interrupt will generate the interrupt when the Stop condition occurs.

In multi-master operation, the SDAx line must be monitored for arbitration to see if the signal level is the expected output level. This check is performed by hardware with the result placed in the BCLxIF bit.

The states where arbitration can be lost are:

- Address Transfer
- Data Transfer
- A Start Condition
- A Repeated Start Condition
- An Acknowledge Condition

25.6.13 MULTI -MASTER COMMUNICATION, BUS COLLISION AND BUS ARBITRATION

Multi-Master mode support is achieved by bus arbitration. When the master outputs address/data bits onto the SDAx pin, arbitration takes place when the master outputs a '1' on SDAx, by letting SDAx float high and another master asserts a '0'. When the SCLx pin floats high, data should be stable. If the expected data on SDAx is a '1' and the data sampled on the SDAx pin is '0', then a bus collision has taken place. The master will set the Bus Collision Interrupt Flag, BCLxIF and reset the I^{2}C port to its Idle state (Figure 25-32).

If a transmit was in progress when the bus collision occurred, the transmission is halted, the BF flag is cleared, the SDAx and SCLx lines are deasserted and the SSPxBUF can be written to. When the user services the bus collision Interrupt Service Routine and if the I^{2}C bus is free, the user can resume communication by asserting a Start condition.

If a Start, Repeated Start, Stop or Acknowledge condition was in progress when the bus collision occurred, the condition is aborted, the SDAx and SCLx lines are deasserted and the respective control bits in the SSPxCON2 register are cleared. When the user services the bus collision Interrupt Service Routine and if the I^{2}C bus is free, the user can resume communication by asserting a Start condition.

The master will continue to monitor the SDAx and SCLx pins. If a Stop condition occurs, the SSPxIF bit will be set.

A write to the SSPxBUF will start the transmission of data at the first data bit, regardless of where the transmitter left off when the bus collision occurred.

In Multi-Master mode, the interrupt generation on the detection of Start and Stop conditions allows the determination of when the bus is free. Control of the I^{2}C bus can be taken when the P bit is set in the SSPxSTAT register, or the bus is Idle and the S and P bits are cleared.

25.6.13.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDAx or SCLx are sampled low at the beginning of the Start condition (Figure 25-33).

b) SCLx is sampled low before SDAx is asserted low (Figure 25-34).

During a Start condition, both the SDAx and the SCLx pins are monitored.

If the SDAx pin is already low, or the SCLx pin is already low, then all of the following occur:

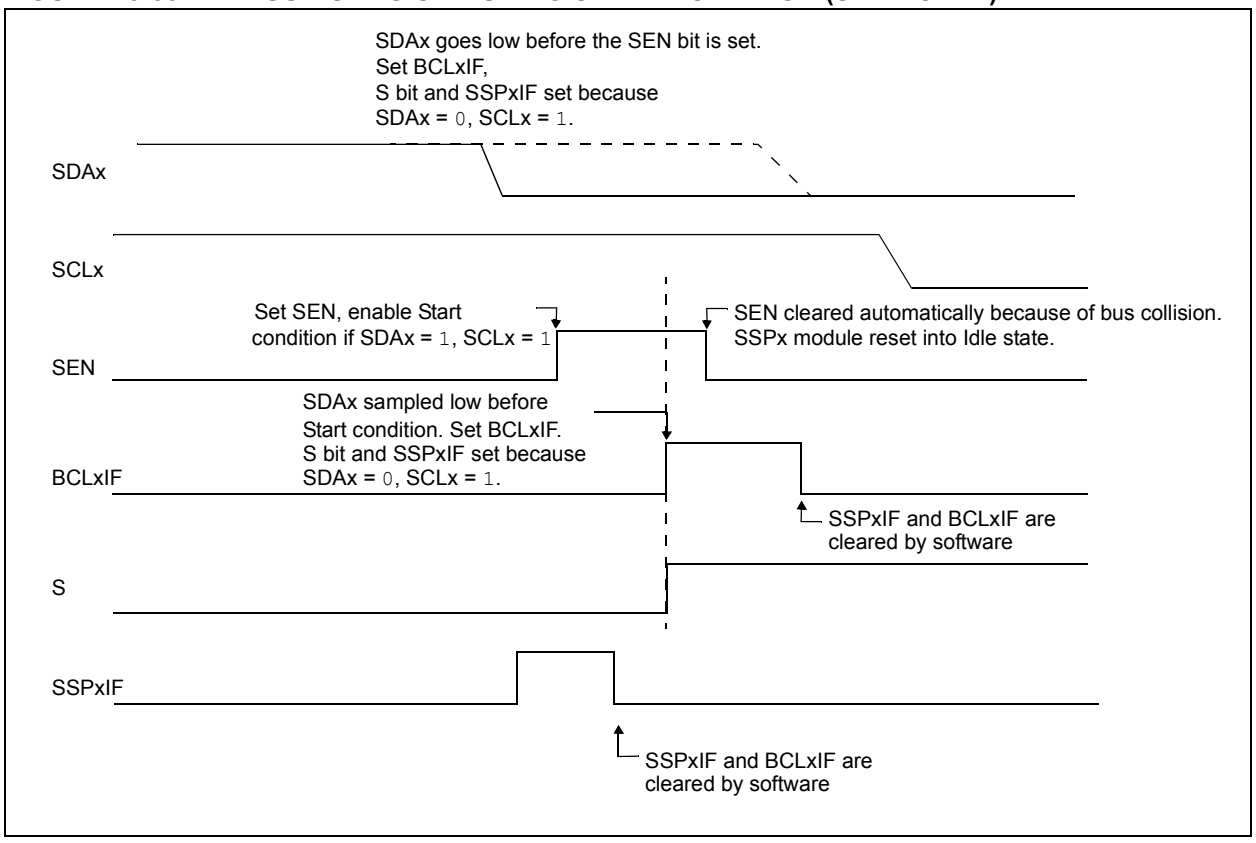
- the Start condition is aborted,
- the BCLxIF flag is set and
- the MSSPx module is reset to its Idle state (Figure 25-33).

The Start condition begins with the SDAx and SCLx pins deasserted. When the SDAx pin is sampled high, the Baud Rate Generator is loaded and counts down. If the SCLx pin is sampled low while SDAx is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDAx pin is sampled low during this count, the BRG is reset and the SDAx line is asserted early (Figure 25-35). If, however, a '1' is sampled on the SDAx pin, the SDAx pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to zero; if the SCLx pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCLx pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDAx before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 25-33: BUS COLLISION DURING START CONDITION (SDAX ONLY)



26.3 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUDCON register selects 16-bit mode.

The SPBRGH, SPBRGL register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TXSTA register and the BRG16 bit of the BAUDCON register. In Synchronous mode, the BRGH bit is ignored.

Table 26-3 contains the formulas for determining the baud rate. Example 26-1 provides a sample calculation for determining the baud rate and baud rate error.

Typical baud rates and error values for various asynchronous modes have been computed for your convenience and are shown in Table 26-3. It may be advantageous to use the high baud rate (BRGH = 1), or the 16-bit BRG (BRG16 = 1) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SPBRGH, SPBRGL register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is Idle before changing the system clock.

EXAMPLE 26-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

$$Desired\ Baud\ Rate = \frac{FOSC}{64([SPBRGH:SPBRGL] + 1)}$$

Solving for SPBRGH:SPBRGL:

$$X = \frac{\frac{FOSC}{Desired\ Baud\ Rate}}{64} - 1$$

$$= \frac{\frac{16000000}{9600}}{64} - 1$$

$$= [25.042] = 25$$

$$Calculated\ Baud\ Rate = \frac{16000000}{64(25 + 1)}$$

$$= 9615$$

$$Error = \frac{Calc.\ Baud\ Rate - Desired\ Baud\ Rate}{Desired\ Baud\ Rate}$$

$$= \frac{(9615 - 9600)}{9600} = 0.16\%$$

26.4 EUSART Synchronous Mode

Synchronous serial communications are typically used in systems with a single master and one or more slaves. The master device contains the necessary circuitry for baud rate generation and supplies the clock for all devices in the system. Slave devices can take advantage of the master clock by eliminating the internal clock generation circuitry.

There are two signal lines in Synchronous mode: a bidirectional data line and a clock line. Slaves use the external clock supplied by the master to shift the serial data into and out of their respective receive and transmit shift registers. Since the data line is bidirectional, synchronous operation is half-duplex only. Half-duplex refers to the fact that master and slave devices can receive and transmit data but not both simultaneously. The EUSART can operate as either a master or slave device.

Start and Stop bits are not used in synchronous transmissions.

26.4.1 SYNCHRONOUS MASTER MODE

The following bits are used to configure the EUSART for Synchronous Master operation:

- SYNC = 1
- CSRC = 1
- SREN = 0 (for transmit); SREN = 1 (for receive)
- CREN = 0 (for transmit); CREN = 1 (for receive)
- SPEN = 1

Setting the SYNC bit of the TXSTA register configures the device for synchronous operation. Setting the CSRC bit of the TXSTA register configures the device as a master. Clearing the SREN and CREN bits of the RCSTA register ensures that the device is in the Transmit mode, otherwise the device will be configured to receive. Setting the SPEN bit of the RCSTA register enables the EUSART.

26.4.1.1 Master Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a master transmits the clock on the TX/CK line. The TX/CK pin output driver is automatically enabled when the EUSART is configured for synchronous transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One clock cycle is generated for each data bit. Only as many clock cycles are generated as there are data bits.

26.4.1.2 Clock Polarity

A clock polarity option is provided for Microwire compatibility. Clock polarity is selected with the SCKP bit of the BAUDCON register. Setting the SCKP bit sets the clock Idle state as high. When the SCKP bit is set, the data changes on the falling edge of each clock. Clearing the SCKP bit sets the Idle state as low. When the SCKP bit is cleared, the data changes on the rising edge of each clock.

26.4.1.3 Synchronous Master Transmission

Data is transferred out of the device on the RX/DT pin. The RX/DT and TX/CK pin output drivers are automatically enabled when the EUSART is configured for synchronous master transmit operation.

A transmission is initiated by writing a character to the TXREG register. If the TSR still contains all or part of a previous character the new character data is held in the TXREG until the last bit of the previous character has been transmitted. If this is the first character, or the previous character has been completely flushed from the TSR, the data in the TXREG is immediately transferred to the TSR. The transmission of the character commences immediately following the transfer of the data to the TSR from the TXREG.

Each data bit changes on the leading edge of the master clock and remains valid until the subsequent leading clock edge.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

26.4.1.4 Synchronous Master Transmission Setup:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 26.3 "EUSART Baud Rate Generator (BRG)"**).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. Disable Receive mode by clearing bits SREN and CREN.
4. Enable Transmit mode by setting the TXEN bit.
5. If 9-bit transmission is desired, set the TX9 bit.
6. If interrupts are desired, set the TXIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
7. If 9-bit transmission is selected, the 9th bit should be loaded in the TX9D bit.
8. Start transmission by loading data to the TXREG register.

LSLF **Logical Left Shift**

Syntax: [*label*] LSLF f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<7>) → C
(f<6:0>) → dest<7:1>
0 → dest<0>

Status Affected: C, Z

Description: The contents of register 'f' are shifted one bit to the left through the Carry flag. A '0' is shifted into the LSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.

LSRF **Logical Right Shift**

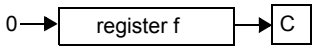
Syntax: [*label*] LSRF f {,d}

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: 0 → dest<7>
(f<7:1>) → dest<6:0>,
(f<0>) → C,

Status Affected: C, Z

Description: The contents of register 'f' are shifted one bit to the right through the Carry flag. A '0' is shifted into the MSb. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register 'f'.



MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Description: The contents of register f is moved to a destination dependent upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example:

```
MOVF    FSR, 0
```

After Instruction
W = value in FSR register
Z = 1

30.3 DC Characteristics

TABLE 30-1: SUPPLY VOLTAGE

PIC16LF1847			Standard Operating Conditions (unless otherwise stated)				
PIC16F1847							
Param. No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D001	VDD	**Supply Voltage**					
			VDDMIN 1.8 2.5	— —	VDDMAX 3.6 3.6	V V	FOSC ≤ 16 MHz: FOSC ≤ 32 MHz **(Note 2)**
D001	VDD		1.8 2.5	— —	5.5 5.5	V V	FOSC ≤ 16 MHz: FOSC ≤ 32 MHz **(Note 2)**
D002*	VDR	**RAM Data Retention Voltage(1)**					
			1.5	—	—	V	Device in Sleep mode
D002*	VDR		1.7	—	—	V	Device in Sleep mode
D002A*	VPOR	**Power-on Reset Release Voltage(3)**	—	1.6	—	V	
D002B*	VPORR	**Power-on Reset Rearm Voltage(3)**					
			—	0.8	—	V	
D002B*	VPORR		—	1.4	—	V	
D003	VFVR	**Fixed Voltage Reference Voltage**	—	1.024	—	V	-40°C ≤ TA ≤ +85°C
D003A	VADFVR	**FVR Gain Voltage Accuracy for ADC**	-8	—	+6	%	1x VFVR, VDD ≥ 2.5V 2x VFVR, VDD ≥ 2.5V 4x VFVR, VDD ≥ 4.75V
D003B	VCDAFVR	**FVR Gain Voltage Accuracy for Comparator and DAC**	-11	—	+7	%	1x VFVR, VDD ≥ 2.5V 2x VFVR, VDD ≥ 2.5V 4x VFVR, VDD ≥ 4.75V
D004*	SVDD	**VDD Rise Rate(2)**	0.05	—	—	V/ms	Ensures that the Power-on Reset signal is released properly.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: PLL required for 32 MHz operation.

3: See Figure 30-3: POR and POR Rearm with Slow Rising VDD.

TABLE 30-2: SUPPLY CURRENT (I_{DD})(1,2) (CONTINUED)

PIC16LF1847		Standard Operating Conditions (unless otherwise stated)					
PIC16F1847							
Param. No.	Device Characteristics	Min.	Typ†	Max.	Units	Conditions	
						V_{DD}	Note
D019		—	3.50	3.70	mA	3.0	F_{OSC} = 32 MHz HFINTOSC **(Note 3)**
		—	4.20	4.30	mA	5.0	
D020		—	3.20	3.50	mA	3.0	F_{OSC} = 32 MHz HS Oscillator **(Note 4)**
		—	3.70	3.90	mA	3.6	
D020		—	3.30	3.60	mA	3.0	F_{OSC} = 32 MHz HS Oscillator **(Note 4)**
		—	3.70	4.10	mA	5.0	
D021		—	252	350	µA	1.8	F_{OSC} = 4 MHz EXTRC **(Note 5)**
		—	480	580	µA	3.0	
D021		—	302	425	µA	1.8	F_{OSC} = 4 MHz EXTRC **(Note 5)**
		—	440	680	µA	3.0	
		—	511	780	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all I_{DD} measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to V_{DD}; $\overline{MCLR}$ = V_{DD}; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: 8 MHz internal oscillator with 4x PLL enabled.

4: 8 MHz crystal oscillator with 4x PLL enabled.

5: For RC oscillator configurations, current through R_{EXT} is not included. The current through the resistor can be extended by the formula $I_R = V_{DD}/2R_{EXT}$ (mA) with R_{EXT} in kΩ.

TABLE 30-3: POWER-DOWN CURRENTS (I_{PD})(1,2) (CONTINUED)

PIC16LF1847		Operating Conditions: (unless otherwise stated) Low-Power Sleep Mode						
PIC16F1847		Low-Power Sleep Mode						
Param. No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							V_{DD}	Note
D027		—	2.0	6.0	8.0	µA	1.8	Cap Sense, Low Power, CPSRM = 0, CPSRNG = 01 **(Note 1)**
		—	5.0	9.0	12.0	µA	3.0	
D027		—	21	41	45	µA	1.8	Cap Sense, Low Power, CPSRM = 0, CPSRNG = 01 **(Note 1)**
		—	23	47	55	µA	3.0	
		—	29	55	68	µA	5.0	
D027A		—	6.0	9.0	10	µA	1.8	Cap Sense, Medium Power, CPSRM = 0, CPSRNG = 10 **(Note 1)**
		—	8.0	13	14	µA	3.0	
D027A		—	21	44	47	µA	1.8	Cap Sense, Medium Power CPSRM = 0, CPSRNG = 10 **(Note 1)**
		—	24	53	60	µA	3.0	
		—	27	57	71	µA	5.0	
D027B		—	13	22	24	µA	1.8	Cap Sense, High Power, CPSRM = 0, CPSRNG = 11 **(Note 1)**
		—	35	65	70	µA	3.0	
D027B		—	21	44	50	µA	1.8	Cap Sense, High Power, CPSRM = 0, CPSRNG = 11 **(Note 1)**
		—	40	68	80	µA	3.0	
		—	50	78	90	µA	5.0	
D028		—	8.0	16	17	µA	1.8	Comparator, Low Power, CxSP = 0 **(Note 1)**
		—	9.0	18	19	µA	3.0	
D028		—	28	45	50	µA	1.8	Comparator, Low Power, CxSP = 0 **(Note 1)**
		—	30	56	61	µA	3.0	
		—	32	60	80	µA	5.0	
D028B		—	28	46	48	µA	1.8	Comparator, Normal Power, CxSP = 1 **(Note 1)**
		—	29	48	50	µA	3.0	
D028B		—	60	80	85	µA	1.8	Comparator, Low Power, CxSP = 1 **(Note 1)**
		—	62	85	90	µA	3.0	
		—	64	90	105	µA	5.0	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The peripheral current is the sum of the base I_{DD} or I_{PD} and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base I_{DD} or I_{PD} current from this limit. Max values should be used when calculating total current consumption.

2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to V_{DD}.

3: ADC oscillator source is FRC.

TABLE 30-20: SPI MODE REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Symbol**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
SP70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK↓ or SCK↑ input	2.25 Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)	1 Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)	1 Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge	100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge	100	—	—	ns	
SP75*	TdoR	SDO data output rise time	—	10	25	ns	3.0V ≤ VDD ≤ 5.5V
			—	25	50	ns	1.8V ≤ VDD ≤ 5.5V
SP76*	TdoF	SDO data output fall time	—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output high-impedance	10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	—	10	25	ns	3.0V ≤ VDD ≤ 5.5V
			—	25	50	ns	1.8V ≤ VDD ≤ 5.5V
SP79*	TscF	SCK output fall time (Master mode)	—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	—	—	50	ns	3.0V ≤ VDD ≤ 5.5V
			—	—	145	ns	1.8V ≤ VDD ≤ 5.5V
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge	1 Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge	—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge	1.5 Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 31-55: COMPARATOR HYSTERESIS, NORMAL-POWER MODE, CxSP = 1, CxHYS = 1

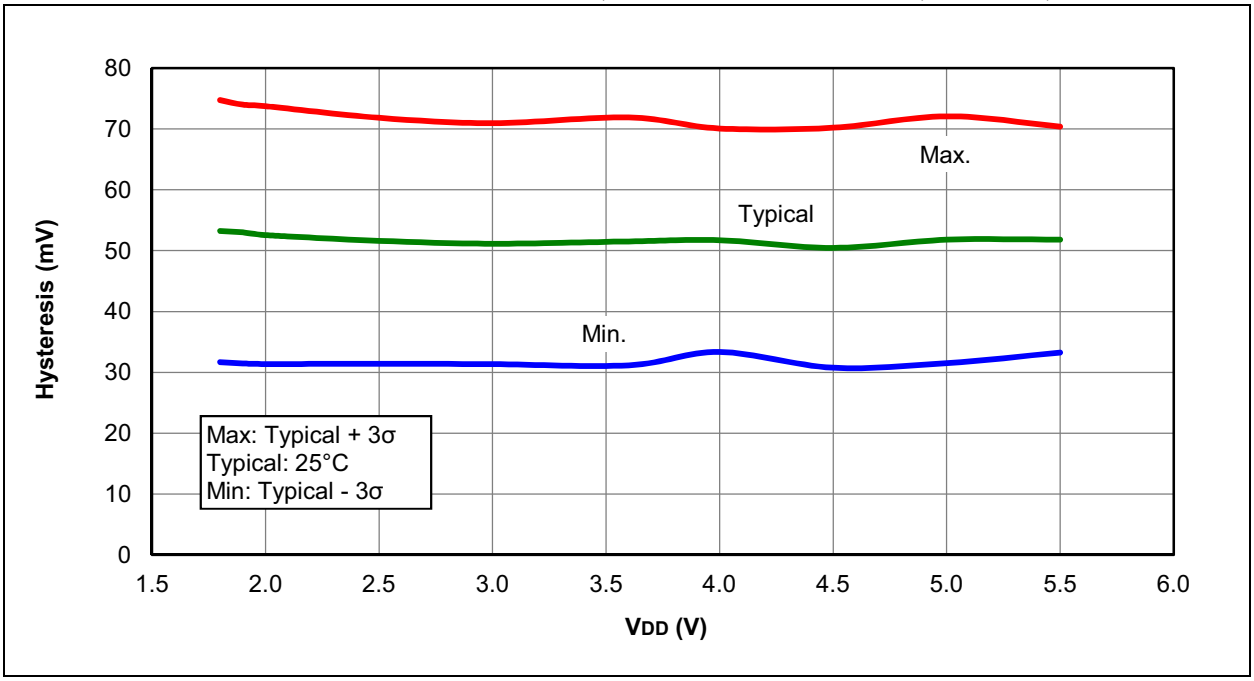
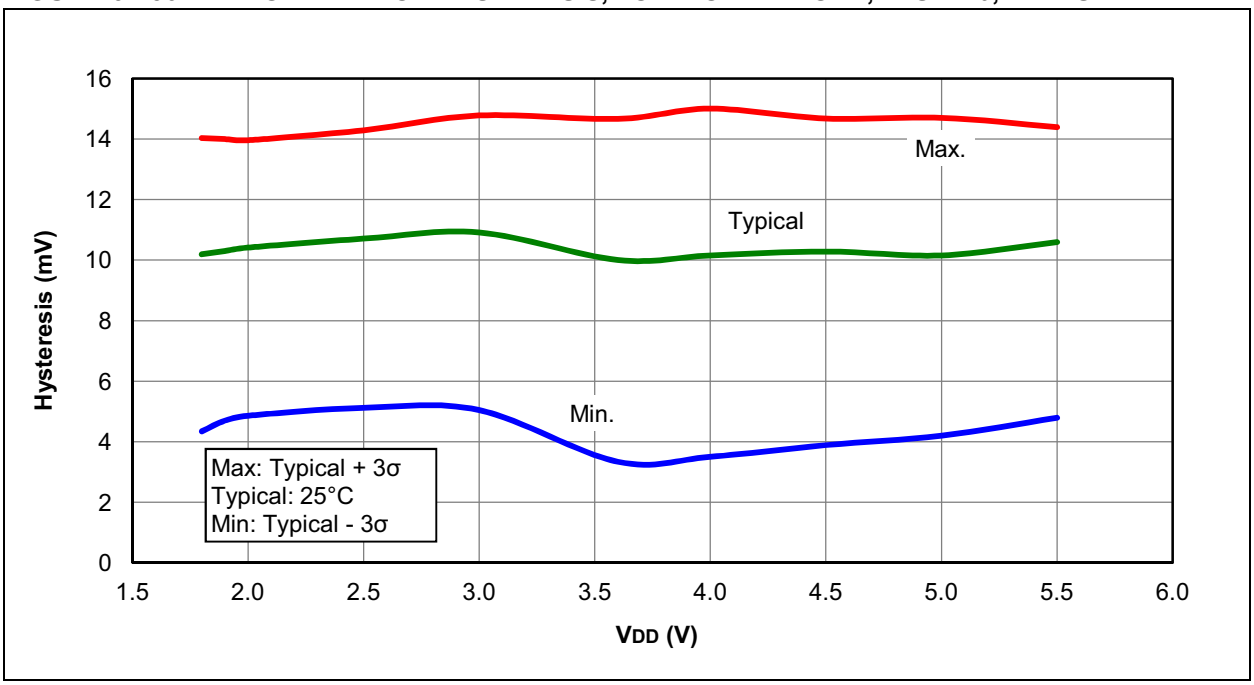
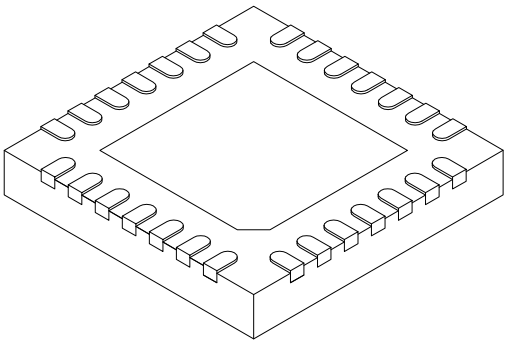


FIGURE 31-56: COMPARATOR HYSTERESIS, LOW-POWER MODE, CxSP = 0, CxHYS = 1



28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M.

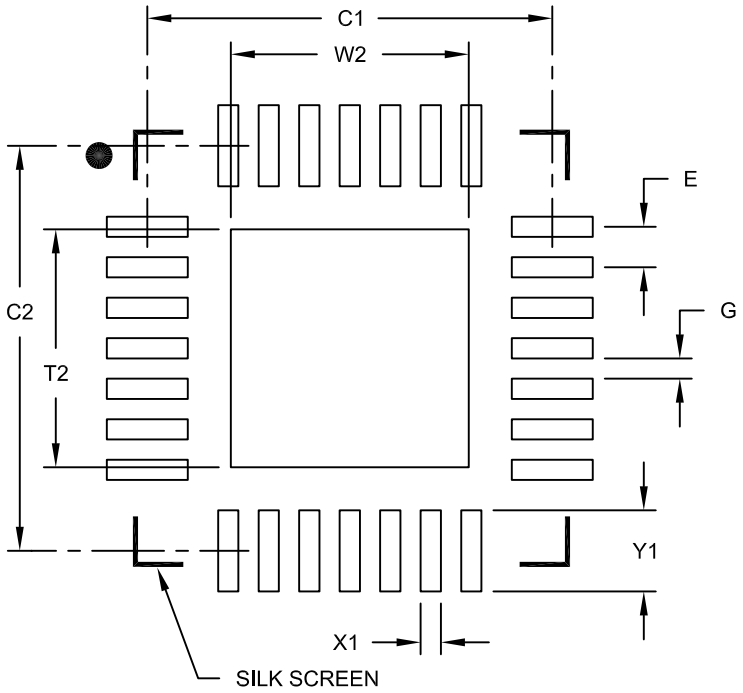
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2

28-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 4x4 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			2.35
Optional Center Pad Length	T2			2.35
Contact Pad Spacing	C1		4.00	
Contact Pad Spacing	C2		4.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2152A

NOTES: